Previous Datasheet 前のデータシート International **ISPR** Rectifier

Next Data Sheet 次のデータシート Data Sheet No. PD-6.057D

IR51HD737

SELF-OSCILLATING HALF-BRIDGE

Features

- Output Power MOSFETs in half-bridge configuration 300V Rated Breakdown Voltage
- High side gate drive designed for bootstrap operation
- Bootstrap diode integrated into package
- Accurate timing control for both Power MOSFETs Matched delay to get 50% duty cycle Matched deadtime of 1.2us
- Internal oscillator with programmable frequency

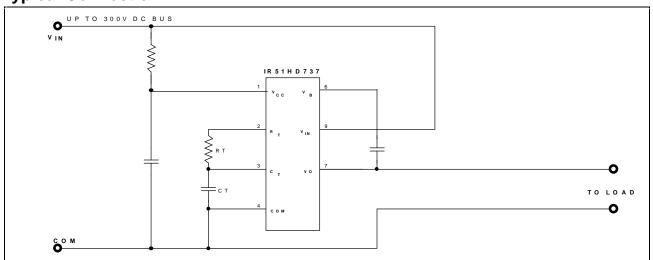
$$f = \frac{1}{1.4 \times (\mathsf{R}\mathsf{T} + 75\Omega) \times \mathsf{C}\mathsf{T}}$$

- Zener clamped Vcc for offline operation
- Half-bridge output is out of phase with R_T

Description

The IR51HD737 is a high voltage, high speed, selfoscillating half-bridge. Proprietary HVIC and latch immune CMOS technologies, along with the HEXFET[®] power MOSFET technology, enable ruggedized single package construction. The front-end features a programmable oscillator which functions similar to the CMOS 555 timer. The supply to the control circuit has a zener clamp to simplify offline operation. The output features two HEXFETs in a half-bridge configuration with an internally set deadtime designed for minimum cross-conduction in the half-bridge. Propagation delays for the high and low side power MOSFETs are matched to simplify use in 50% duty cycle applications. The device can operate up to 300 volts.

Typical Connection



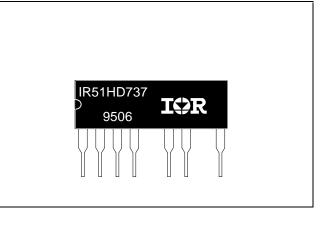


Product Summary

V _{IN} (max)	300V
Duty Cycle	50%
Deadtime	1.2µs
R _{DS(on)}	0.75Ω
P _D (T _A = 25 °C)	2.0W

Package

Index











IR51HD737

Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V _{IN}	High Voltage Supply	-0.3	300	
VB	High Side Floating Supply Absolute Voltage	-0.3	325	
VO	Half-Bridge Output Voltage	-0.3	V _{IN} + 0.3	V
V _{RT}	R _T Voltage	-0.3	V _{CC} + 0.3	
V _{CT}	C _T Voltage	-0.3	V _{CC} + 0.3	
Icc	Supply Current (Note 1)		25	mA
I _{RT}	R _T Output Current	-5	5	Ì
dv/dt	Peak Diode Recovery dv/dt		3.4	V/ns
PD	Package Power Dissipation @ $T_A \le +25^{\circ}C$		2.00	W
R _{0JA}	Thermal Resistance, Junction to Ambient		60	°C/W
TJ	Junction Temperature	-55	150	
Ts	Storage Temperature	-55	150	°C
TL	Lead Temperature (Soldering, 10 seconds)		300	

Recommended Operating Conditions

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
VB	High Side Floating Supply Absolute Voltage	VO + 10	$VO + V_{CLAMP}$	
VIN	High Voltage Supply		300	V
VO	Half-Bridge Output Voltage	-5	300	
ID	Continuous Drain Current $(T_A = 25^{\circ}C)$		1.3	Α
	(T _A = 85°C)		0.8	
Icc	Supply Current (Note 1)		5	mA
TA	Ambient Temperature	-40	125	°C

Note 1: Because of the IR51H737's application specificity toward off-line supply systems, this IC contains a zener clamp structure between the chip V_{CC} and COM which has a nominal breakdown voltage of 15.6V. Therefore, the IC supply voltage is normally derived by current feeding the V_{CC} lead (typically by means of a high value resistor connected between the chip V_{CC} and the rectified line voltage and a local decoupling capacitor from V_{CC} to COM) and allowing the internal zener clamp circuit to determine the nominal supply voltage. Therefore, this circuit should not be driven by a DC, low impedance power source of greater than V_{CLAMP}.









Dynamic Electrical Characteristics

 V_{BIAS} (V_{CC}, V_B) = 12V unless otherwise specified.

	Parameter	TA	= 25°C)		
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
t _{rr}	Reverse Recovery Time (MOSFET Body Diode)		320		ns	I _F = 1.3 A
Q _{rr}	Reverse Recovery Charge (MOSFET Body Diode)		1.5		μC	di/dt = 100A/µs
DT	Deadtime, LS Turn-Off to HS Turn-On & HS Turn-Off to LS Turn-On		1.2		μs	
D	R⊤ Duty Cycle		50		%	f _{OSC} = 20 kHz

Static Electrical Characteristics

 V_{BIAS} (V_{CC}, V_B) = 12V unless otherwise specified.

	Parameter	$T_{A} = 25^{\circ}$				
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
Supply	Characteristics					
V _{CCUV+}	V _{CC} Supply Undervoltage Positive Going Threshold		8.4		V	
V _{CCUV} -	V _{CC} Supply Undervoltage Negative Going Threshold		8.0			
lqcc	Quiescent V _{CC} Supply Current		300		μA	
VCLAMP	V _{CC} Zener Shunt Clamp Voltage		15.6		V	$I_{CC} = 5 \text{ mA}$
Floating	Supply Characteristics		.,			·
I _{QBS}	Quiescent V _{BS} Supply Current		30		μA	
los	Offset Supply Leakage Current 5	0	V			$_{B} = V_{IN} = 300V$
Oscillate	or I/O Characteristics					
fosc	Oscillator Frequency		20		kHz	$\begin{array}{l} R_{T}=35.7 \; k\Omega, \\ C_{T}=1 \; nF \end{array}$
			100			$R_T = 7.04 \text{ k}\Omega,$ $C_T = 1 \text{ nF}$
I _{CT}	C _T Input Current		0.001	1.0	μA	
VCTUV	C _T Undervoltage Lockout	100		2.5	V < V	cc < V _{CCUV+}
V _{RT+}	R_T High Level Output Voltage, V _{CC} - R_T		20			I _{RT} = -100 μA
			200		mV	I _{RT} = -1 mA
V _{RT} -	R _T Low Level Output Voltage		20			I _{RT} = 100 μA
			200]	I _{RT} = 1 mA
V _{RTUV}	RT Undervoltage Lockout, V _{CC} - RT		100]	2.5V < V _{CC} < V _{CCUV+}
V _{CT+}	2/3 V _{CC} Threshold		8.0		V	
V _{CT} -	1/3 V _{CC} Threshold		4.0		1	
Output (Characteristics	•				
R _{DS(on)}	Static Drain-to-Source On-Resistance		0.75		Ω	I _D = 800mA
V_{SD}	Diode Forward Voltage 0.8	-			V	T _i = 150 ⁰C

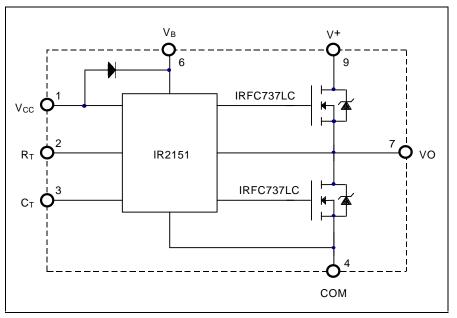








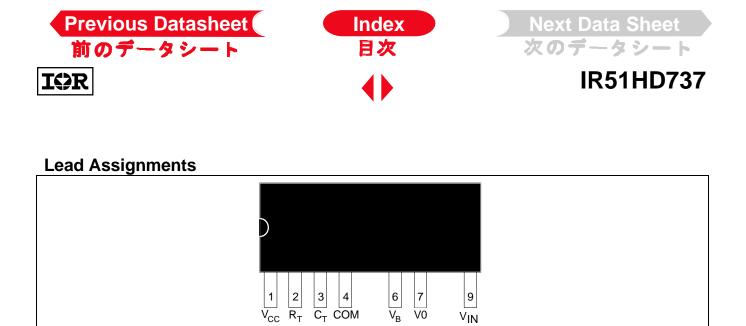
Functional Block Diagram



Lead Definitions

	Lead			
Symbol	Description			
V _{CC}	Logic and internal gate drive supply voltage. An internal zener clamp diode at 15.6 V nominal is included to allow the Vcc to be current fed directly from V_{IN} typically by means of a high value resistor.			
R⊤	Oscillator timing resistor input; a resistor is connected from R_T to C_T . R_T is out of phase with the half-bridge output (VO).			
CT	Oscillator timing capacitor output; a capacitor is connected from C_T to COM in order to program the oscillator frequency according to the following equation:			
	$f = \frac{1}{1.4 \times (RT + 75\Omega) \times CT}$			
	where 75 Ω is the effective impedance of the R _T output stage.			
VB	High side gate drive floating supply. For bootstrap operation a high voltage fast recovery diode is needed to feed from V_{CC} to V_B .			
V _{IN}	High voltage supply.			
VO	Half-bridge output.			
COM	Logic and low side of half-bridge return.			





9 Lead SIP w/o Leads 5 & 8 IR51HD737

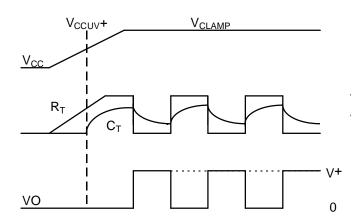


Figure 1. Input/Output Timing Diagram

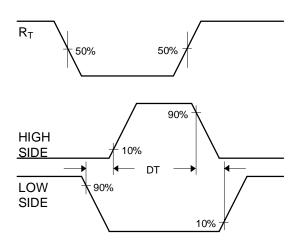
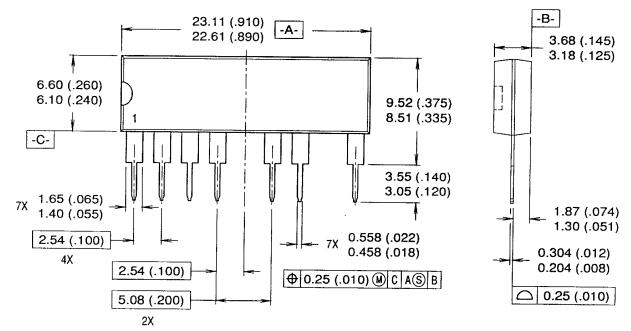


Figure 2. Deadtime Waveform Definitions







NOTES:

- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Package Outline

International

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Data and specifications subject to change without notice.

Sales Offices, Agents and Distributors in Major Cities Throughout the World.

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